



## N-Channel 100-V (D-S) MOSFET

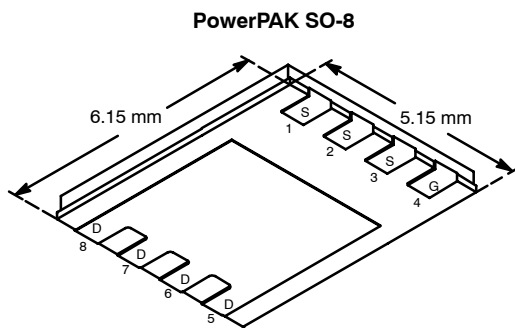
PRODUCT SUMMARY		
V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)
100	0.025 @ V <sub>GS</sub> = 10 V	9.3
	0.028 @ V <sub>GS</sub> = 6.0 V	8.8

### FEATURES

- TrenchFET® Power MOSFETS
- New Low Thermal Resistance PowerPAK® Package with Low 1.07-mm Profile
- PWM Optimized for Fast Switching
- 100% R<sub>g</sub> Tested

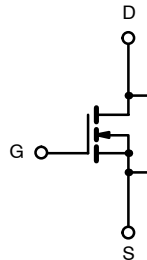
### APPLICATIONS

- Primary Side Switch for High Density DC/DC
- Telecom/Server 48-V, Full-/Half-Bridge DC/DC
- Industrial and 42-V Automotive



Bottom View

Ordering Information: Si7456DP-T1



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C UNLESS OTHERWISE NOTED)					
Parameter	Symbol	10 secs	Steady State	Unit	
Drain-Source Voltage	V <sub>DS</sub>	100		V	
Gate-Source Voltage	V <sub>GS</sub>	± 20			
Continuous Drain Current (T <sub>J</sub> = 150°C) <sup>a</sup>	I <sub>D</sub>	T <sub>A</sub> = 25°C	9.3	5.7	A
		T <sub>A</sub> = 85°C	6.7	4.1	
Pulsed Drain Current	I <sub>DM</sub>	40			
Avalanche Current	I <sub>AS</sub>	30			
Single Avalanche Energy (Duty Cycle ≤ 1%)	E <sub>AS</sub>	45		mJ	
L = 0.1 mH					
Continuous Source Current (Diode Conduction) <sup>a</sup>	I <sub>S</sub>	4.3	1.6	A	
Maximum Power Dissipation <sup>a</sup>	P <sub>D</sub>	T <sub>A</sub> = 25°C	5.2	1.9	W
		T <sub>A</sub> = 85°C	2.7	1.0	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150		°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	R <sub>thJA</sub>	t ≤ 10 sec	19	24	°C/W
		Steady State	52	65	
Maximum Junction-to-Case	R <sub>thJC</sub>	1.5	1.8		

Notes

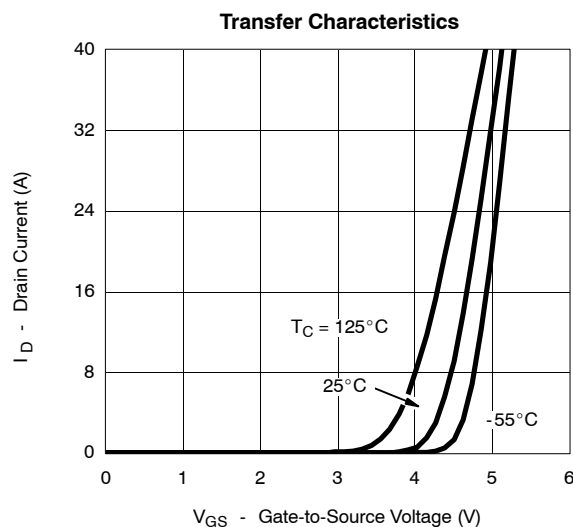
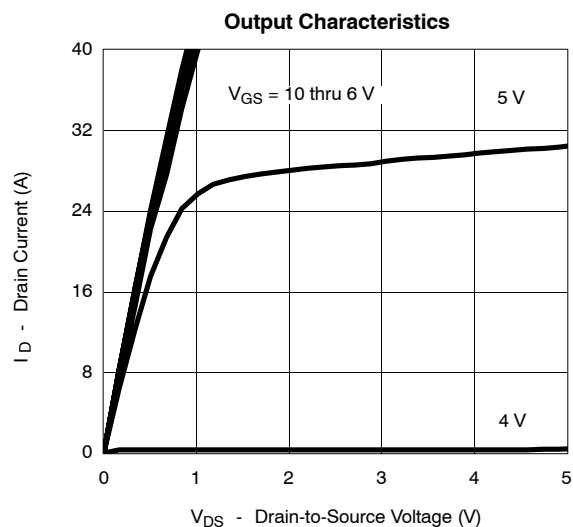
a. Surface Mounted on 1" x 1" FR4 Board.

**SPECIFICATIONS (T<sub>J</sub> = 25 °C UNLESS OTHERWISE NOTED)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2			V
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	μA
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 85 °C			20	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 5 V, V <sub>GS</sub> = 10 V	40			A
Drain-Source On-State Resistance <sup>a</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 9.3 A		0.021	0.025	Ω
		V <sub>GS</sub> = 6.0 V, I <sub>D</sub> = 8.8 A		0.023	0.028	
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 9.3 A		35		S
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>S</sub> = 4.3 A, V <sub>GS</sub> = 0 V		0.8	1.2	V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 9.3 A		36	44	nC
Gate-Source Charge	Q <sub>gs</sub>			10		
Gate-Drain Charge	Q <sub>gd</sub>			8.6		
Gate Resistance	R <sub>g</sub>		0.5	1.27	2.1	Ω
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 50 V, R <sub>L</sub> = 50 Ω I <sub>D</sub> ≅ 1 A, V <sub>GEN</sub> = 10 V, R <sub>G</sub> = 6 Ω		20	40	ns
Rise Time	t <sub>r</sub>			10	20	
Turn-Off Delay Time	t <sub>d(off)</sub>			46	90	
Fall Time	t <sub>f</sub>			26	50	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 4.3 A, di/dt = 100 A/μs		50	80	

## Notes

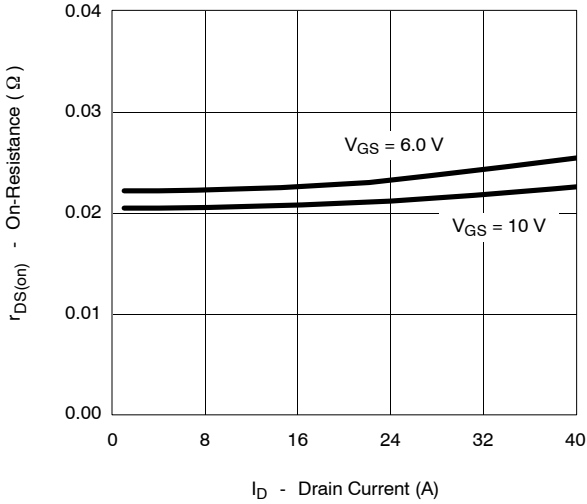
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.  
b. Guaranteed by design, not subject to production testing.

**TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)**

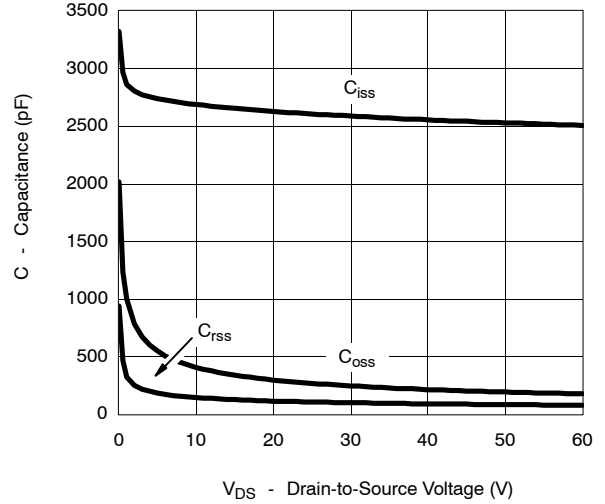


**TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**

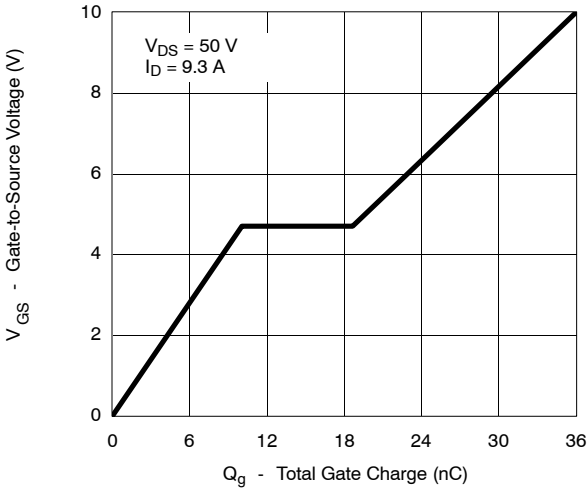
**On-Resistance vs. Drain Current**



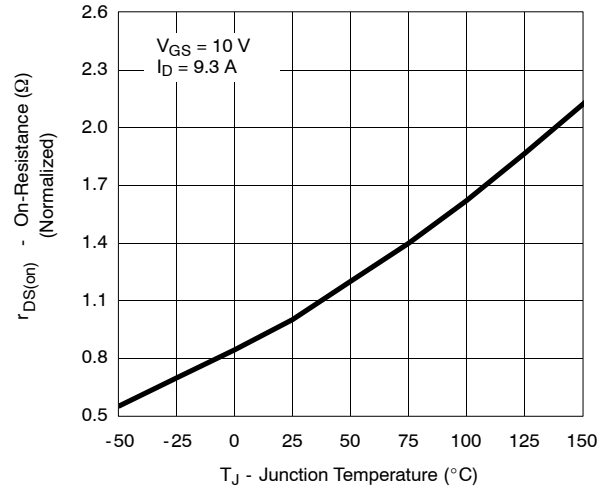
**Capacitance**



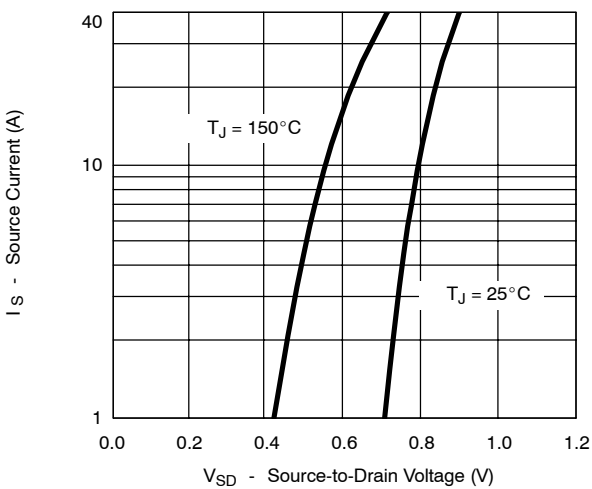
**Gate Charge**



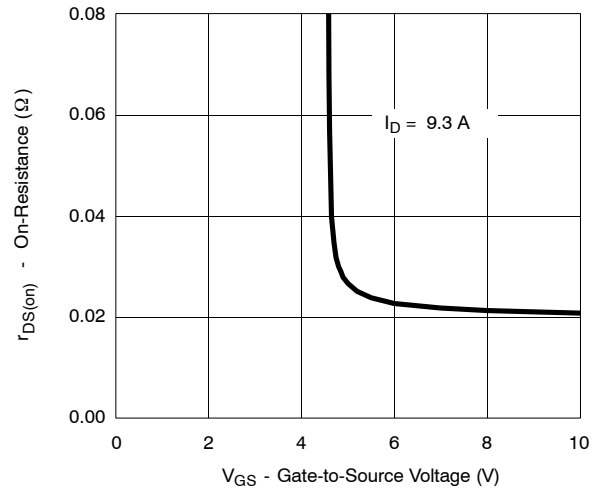
**On-Resistance vs. Junction Temperature**



**Source-Drain Diode Forward Voltage**



**On-Resistance vs. Gate-to-Source Voltage**



**TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)**

